		221219006.1		PCN Date:		te:	December 21, 2022			
I ITIA'					v Fab site (RFAB) using qualified Process Technology, Die Revision, and additional Assembly site/BOM options for select devices					
					Site/ bo	וייוי טן	JUIOII	5 101 5	elect devices	
Cus	tomer	Contact:		<u>PCN</u>	<u>Manager</u>		Dep	ot:		Quality Services
Proposed 1 st Ship Date:					ple requests cepted until:			January 20, 2023*		
*Sa	mple i	equests rece	ived	afte	r January 20, 202	3 will r	not b	e su	pport	ed.
Cha	nge Ty	/pe:								
\boxtimes	Assem	bly Site			Assembly Process			\boxtimes	Asser	mbly Materials
\boxtimes	Desigr	า			Electrical Specifical	tion			Mechanical Specification	
	Test S	Site			Packing/Shipping/Labeling				Test Process	
	Wafer	Bump Site			☐ Wafer Bump Material				Wafer Bump Process	
			₩afer Fab Materials			\boxtimes	Wafer Fab Process			
			☐ Part number change							
	PCN Details									
Des	crintio	n of Change:	,				,	,		

Texas Instruments is pleased to announce the qualification of a new fab & process technology (RFAB, LBC9) and assembly (MLA) site/BOM options for selected devices as listed below in the product affected section.

	Current Fa	b Site	New Fab Site			
Fab Site	Process	Process Wafer Diameter		Process	Wafer Diameter	
SFAB	JI1	150 mm	RFAB	LBC9	300 mm	

The die was also changed as a result of the process change.

Construction Differences are as follows:

Group 1 - BOM option at MLA

Group 1 Borroption at 1121		
	Current	Additional
Wire type	0.8mil/0.96mil Au, 0.96mil Cu	0.8mil Cu

Group 2 - MLA as an additional Assembly site

	MEX	TAI	MLA
Mount Compound	4147858	4042500	4147858
Bond Wire Composition/diamater	Au/0.96 or 0.8 mil or Cu/0.96 or 0.8 mil	Au/0.96 mil	Cu/0.8 mil
Mold Compound	4205694	4205694	4211880

The associated datasheet changes were notified in a separate Datasheet change notification on 12/19/2022 (Notification# 20221219008.0) as shown below:



TL071, TL071A, TL071B, TL071H TL072, TL072A, TL072B, TL072H, TL072M TL074, TL074A, TL074B, TL074H, TL074M SLOS080U - SEPTEMBER 1978 - REVISED DECEMBER 2022

Changes from Revision T (December 2021) to Revision U (December 2022)

Page

- Changed Absolute Maximum Ratings, ESD Ratings, Recommended Operating Conditions, and Thermal
- Changed Electrical Characteristics tables by merging TL07xC, TL07xAC, TL07xBC, TL07xI, and TL07xM

- Changed THD+N for all non-PS/non-NS packages and all non-TL07xM devices to 0.00012%......18

These changes may be reviewed at: http://www.ti.com/product/TL071

Qual details are provided in the Qual Data Section.

Reason for Change:

These changes are part of our multiyear plan to transition products from our 150-milimeter factories to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings:

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☑ No Change	☑ No Change	⊠ No Change	⊠ No Change

Changes to product identification resulting from this PCN:

Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City	
SH-BIP-1	SHE	USA	Sherman	
RFAB RFB		USA	Richardson	

Die Rev:

Current New

Die Rev [2P]	Die Rev [2P]
C, F, G, -	A, B

Assembly Site Information:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
TI Mexico	MEX	MEX	Aguascalientes
TI Taiwan	TI Taiwan TAI		Chung Ho, New Taipei City
MLA	MLA	MYS	Kuala Lumpur

Sample product shipping label (not actual product label):

MADE IN: Malaysia 2DC: 20:

MSL 2 /260C/1 YEAR SEAL DT MSL 1 /235C/UNLIM 03/29/04

OPT: ITEM:

LBL: 5A (L)TO:1750



(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T)LOT: 3959047MLA (4W) TKY(1T) 7523483SI2

(2P) REV: (20L) CSO: SHE (21L) CCO:USA (22L) ASO: MLA (23L) ACO: MYS

Product Affected:

Group 1 device list - RFAB/Process migration and BOM Option in MLA:

or oup I device list	ita 715/ i roccoo iiiigia	cion ana borr opcion i	
LF353P	TL072CP	TL081ACP	TL082IPE4
LF353PE4	TL072CPE4	TL081BCP	TL084ACDR
TL071ACP	TL072IP	TL081CP	TL084ACDRE4
TL071BCP	TL072IPE4	TL081CPE4	TL084ACDRG4
TL071CP	TL074CN	TL081IP	TL084CDR
TL071CPE4	TL074CNE4	TL082ACP	TL084CDRG4
TL071IP	TL074CPWR	TL082CP	TL084CN
TL071IPE4	TL074CPWRE4	TL082CPE4	TL084CNE4
TL072ACP	TL074CPWRG4	TL082IP	TL084CPWR
TL072ACPE4			

Group 2 device list - RFAB/Process migration and adding MLA Assembly site:

LF347BDR	TL074ACNE4	TL074IDRE4	TL084BCNE4
LF347BN	TL074BCDR	TL074IDRG4	TL084IDR
LF347DR	TL074BCDRE4	TL074IN	TL084IDRE4
LF347DRG4	TL074BCDRG4	TL075IDR	TL084IDRG4
LF347N	TL074BCN	TL084ACN	TL084IN
LF347NE4	TL074BCNE4	TL084BCDR	TL084INE4
TL074ACDR	TL074CDR	TL084BCDRG4	TL084QDR
TL074ACDRE4	TL074CDRG4	TL084BCN	TL084QDRG4
TL074ACN	TL074IDR		

For alternate parts with similar or improved performance, please visit the product page on TI.com

Qualification Report Approve Date 19-MAY -2022

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	#	Test Name	Condition	Duration	Qual Device: TL074HIPWR	QBS Package Reference: <u>OPA4991QPWRQ1</u>	QBS Product Reference: TL074HIPWR
HAST	A2	Biased HAST	110C/85%RH	264 Hours	-	1/77/0	-
HAST	A2	Biased HAST	110C/85%RH	264 Hours	-	2/154/0	-
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	1/77/0
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	1/77/0
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	3/231/0	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	1/77/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	2/154/0	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	2/90/0	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	1/77/0
PD	C4	Physical Dimensions	Cpk>1.67	-	-	1/10/0	-
ESD	E2	ESD CDM	-	1500 Volts	-	1/3/0	-
ESD	E2	ESD HBM	-	4000 Volts	-	1/3/0	-
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	3/90/0	-

- · QBS: Qual By Similarity
- Qual Device TL074HIPWR is qualified at MSL1 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

Qualification Report Approve Date 26-OCTOBER -2022

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	#	Test Name	Condition	Duration	Qual Device: <u>TL071CP</u>	QBS Reference: <u>OPA4990IDR</u>	QBS Reference: <u>LM358BIDR</u>	QBS Reference: <u>NE5532P</u>	QBS Reference: <u>TLC339IN</u>
HAST	A2	Biased HAST	130C	96 Hours	-	3/231/0	3/231/0	3/231/0	-
UHAST	A3	Autoclave	121C, 2 atm	96 Hours	-	3/231/5 ¹	-	-	3/231/0
UHAST	A3	Unbiased HAST	130C	96 Hours	1/77/0	-	3/231/0	-	-
TC	A4	Temperature Cycle	-65/150C	500 Cycles	1/77/0	3/231/0	3/231/0	-	3/231/0
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	3/231/0	3/231/0	-	3/231/0
HTOL	B1	Life Test	150C	300 Hours	-	3/231/10 ^{2,3}	3/231/0	3/231/0	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	1/800/0	-	-	-
SD	C3	PB-Free Solderability	8 Hours Steam Age	-	-	-	-	3/66/0	3/66/0
ESD	E2	ESD CDM	-	250 Volts	-	-	3/9/0	-	-
ESD	E2	ESD HBM	-	1000 Volts	-	-	3/9/0	-	-
LU	E4	Latch-Up	Per JESD78	-	-	3/18/0	3/18/0	-	-
CHAR	E5	Electrical Characterization	Min, Typ, Max Temp	-	-	3/90/0	3/90/0	-	-

- · QBS: Qual By Similarity
- Qual Device TL071CP is qualified at NOT CLASSIFIED NOT CLASSIFIED
- . Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47:-55C/125C/700 Cycles and -65C/150C/500 Cycles
- Note: This qualification also covers the following devices TL071ACP TL071BCP TL071CP TL071IP TL081ACP TL081BCP TL081CP TL081IP

Quality and Environmental data is available at Tl's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

TI Qualification ID: R-NPD-2210-104

- [1]-Discounted
- [3]-Discounted

Qualification Report Approve Date 19-MAY -2022

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	#	Test Name	Condition	Duration	Qual Device: TL074HIDR	Product QBS Reference: <u>TL074HIDR</u>	Package QBS Reference: <u>OPA4991IDR</u>
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	1/77/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	1/77/0
HTOL	B1	Life Test	150C	300 Hours	-	1/77/0	-
ESD	E2	ESD CDM	-	1500 Volts	-	3/9/0	-
ESD	E2	ESD HBM	-	1500 Volts	-	3/9/0	-
LU	E4	Latch-Up	Per JESD78	-	-	3/9/0	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	-	3/90/0	-

- QBS: Qual By Similarity
- Qual Device TL074HIDR is qualified at MSL1 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

Qualification Report Approve Date 17-OCTOBER -2022

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	#	Test Name	Condition	Duration	Qual Device: TL072CP	QBS Reference: OPA4990IDR	QBS Reference: LM2904BQDRQ1	QBS Reference: <u>NE5532P</u>	QBS Reference: UCC37322P	QBS Reference: TL072HIDR
HAST	A2	Biased HAST	130C	96 Hours	-	3/231/0	3/231/0	3/231/0	-	-
UHAST	A3	Autoclave	121C, 2 atm	96 Hours	-	3/231/5 ¹	-	-	3/231/0	-
UHAST	A3	Unbiased HAST	130C	192 Hours	-	-	3/231/0	-	-	-
TC	A4	Temperature Cycle	-65/150C	500 Cycles	-	3/231/0	3/231/0	-	3/231/0	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	3/231/0	3/135/0	-	3/231/0	-
HTOL	B1	Life Test	150C	300 Hours	-	3/231/10 ^{2,3}	3/231/0	3/231/0	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	1/800/0	3/2400/4 ^{4,5}	-	-	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0	-	-	-
SD	C3	PB-Free Solderability	8 Hours Steam Age	-	-	-	-	3/66/0	3/66/0	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	3/30/0	-	-	-
ESD	E2	ESD CDM	-	1500 Volts	-	-	-	-	-	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	-	-	3/9/0	-	-	1/3/0
LU	E4	Latch-Up	Per JESD78	-	-	3/18/0	-	-	-	1/3/0
CHAR	E5	Electrical Characterization	Min, Typ, Max Temp	-	1/30/0	3/90/0	-	-	-	1/30/0

- · Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- . The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles
- Note: This qualification also covers the following devices TL082IP TL082CP TL082ACP TL072IP TL072CP TL072ACP LF353P

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Ph-free Status:

Qualified Pb-Free(SMT) and Green

TI Qualification ID: R-CHG-2108-066

[1]-Mechanical damage from mis-handling @ test.

[2,3]-Faulty BI sockets.
[4,5]-Precon and ELFR fails due to a defect screenable at production test.

For questions regarding this notice, e-mails can be sent to the contact shown below or your local Field Sales Representative.

Location	E-Mail			
WW Change Management Team	PCN www admin_team@list.ti.com			

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